



Tohoku University

“TIE” Summer Program 2026

- Digital Transformation & Entrepreneurship -

June 29 - July 24, 2026

About

“TIE” Summer Program is a four-week program hosted by the School of Engineering at Tohoku University. As the name “TIE” (Technology, Innovation, and Entrepreneurship) suggests, the program focuses on creating innovative solutions through technology. With an emphasis on Digital Transformation, participants will explore its core technologies and related societal challenges, and design business ideas to address real-world issues in Japan. Cultural activities and field trips also provide opportunities to understand local needs and gain insights for developing meaningful solutions.

What will you learn?



WEEK 1
Problem Identification + Digital Society

Understand the foundations of a digital society and identify real-world challenges shaped by digital transformation



WEEK 2
Problem Analysis & Solution Design

Analyze challenges using digital tools and entrepreneurial methods, and design your solutions



WEEK 3
Business Model Canvas & Prototype

Turn your idea into a business model and develop a prototype of your solution



WEEK 4
Pitch Competition

Present your solution in a final pitch and demonstrate its impact

Program Venue

Tohoku University
in Sendai city, Japan

+ field trips to other cities in Tohoku region



Tohoku University has engaged in world-class education and research activities since its founding in 1907, and has been ranked No.1 in Japan for five consecutive years. The School of Engineering has grown into one of Japan’s largest engineering hubs, driving high-impact research in materials, energy, AI, and beyond.



Requirements

- Primarily open to master's-level students (over 3rd year undergraduate students are also welcome)
- As the program is conducted entirely in English, participants should have a good command of English (no Japanese language ability is required)
- No prior IT knowledge is required, but it would be beneficial
- Beginners in entrepreneurship are welcome

Program Fee *Non-refundable

200,000 JPY
/ participant

The fee includes:

- Tuition
- Japanese cultural program
- Field trips
- Social activities with Tohoku University students
- Certificate of completion
- Welcome and farewell parties

Accommodation & Social Activities

Participants should choose between a hotel in downtown or a homestay. Accommodation costs are the responsibility of participants.

- Hotels: approx. 270,000 – 320,000 JPY (varies depending on the hotel)
- Homestay: approx. 160,000 JPY (4,950 JPY per night + 22,000 JPY of arrangement fee)

Participants are also welcome to join social activities organized by Tohoku University students, such as city tours, izakaya dinners, karaoke nights, and sports activities. Any costs related to these activities will be covered by participants.

Apply Now Deadline: May 10, 2026

▶ Scan the QR code to access the application form

Application link: <https://forms.gle/26kayaR6K7jYqB4C9>



What's next?

May 15 : Result notification (by email)

May 30 : Submission of a copy of travel insurance certificate and program fee payment (online payment by a credit card)

* A student visa is not required. Many nationalities do not need a visa to enter Japan for this program; however, depending on your nationality, a visa may be required.

Connect our team

“TIE” Summer Program Team, School of Engineering, Tohoku University



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